



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D  <i>* : Required Field</i>

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2014-04-02
<b>Contact Name *</b>	Refer to "Supplier Comment" section	<b>Contact Title</b>	Refer to "Supplier Comment" section
<b>Contact Phone *</b>	Refer to "Supplier Comment" section	<b>Contact Email *</b>	Refer to "Supplier Comment" section
<b>Authorized Representative *</b>	Antonella Lanzafame	<b>Representative Title</b>	AMS & IPD Materials Declaration Champion
<b>Representative Phone *</b>	Refer to "Supplier Comment" section	<b>Representative Email *</b>	Refer to "Supplier Comment" section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/internet/com/support/online_tech_support.jsp">http://www.st.com/internet/com/support/online_tech_support.jsp</a>		

**Uncertainty Statement**

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**Legal Statement**

<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard
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**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	HNRO*Z71Q81Y	A	ZA41	2014-04-02
Amount	UoM	Unit type	ST ECOPACK Grade	
15.50	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used c	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
NAC	1.75,1.75,0.85	2	NAC	
Comment	DO-216AA; MD valid for CP:STPS1L40M.			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	false
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-16th December 2013				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	HNRO*Z71Q81Y					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Silicon Die	Other Organic Materials	3.887	mg	Supplier	Silicon die	Silicon	7440-21-3		3.808	mg	979675	245677
Silicon Die				Supplier	die metallization	Aluminium(Al)	7429-90-5		0.045	mg	11577	2903
Silicon Die				Supplier	die metallization	Titanium (Ti)	7440-32-6		0.002	mg	515	129
Silicon Die				Supplier	die metallization	Nickel (Ni)	7440-02-0		0.026	mg	6689	1677
Silicon Die				Supplier	die metallization	Gold (Au)	7440-57-5		0.006	mg	1544	387
Leadframe	Copper & its alloys	192.44	mg	supplier	alloy	Copper (Cu)	7440-50-8		191.299	mg	994071	12341871
Leadframe				supplier	alloy	Iron (Fe)	7439-89-6		0.192	mg	998	12387
Leadframe				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.057	mg	296	3677
Leadframe				supplier	coating	Nickel (Ni)	7440-02-0		0.884	mg	4594	57032
Leadframe				supplier	coating	Phosphorus (P)	7723-14-0		0.008	mg	42	516
Die Attach	Other inorganic materials	1.881	mg	R	Lead/Lead Compounds	Lead (Pb)	7439-92-1	Lead in high melting	1.796	mg	954811	115871
Die Attach				supplier	soft solder	Silver (Ag)	7440-22-4		0.047	mg	24987	3032
Die Attach				supplier	soft solder	Tin (Sn)	7440-31-5		0.038	mg	20202	2452
Bonding wire	Other inorganic materials	0.77	mg	supplier	Bonding wire	Aluminium (Al)	7429-90-5		0.767	mg	996104	49484
Bonding wire				supplier	Bonding wire	Magnesium (Mg)	7439-95-4		0.003	mg	3896	194
Encapsulation	Other Organic Materials	205.529	mg	supplier	Moulding Compound	Silica, vitreous	60676-86-0		164.423	mg	799999	10607935
Encapsulation				supplier	Moulding Compound	Epoxy Cresol Novolak	29690-82-2		14.387	mg	70000	928194
Encapsulation				supplier	Moulding Compound	Phenol resin	9003-35-4		8.221	mg	39999	530387
Encapsulation				supplier	Moulding Compound	Biphenyl epoxy resin	85954-11-6		12.332	mg	60001	795613
Encapsulation				supplier	Moulding Compound	Antimony Trioxide	1309-64-4		2.466	mg	11998	159097